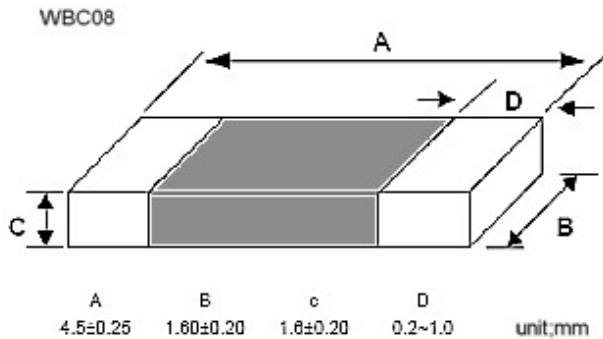




High Current Multi Layer Chip Bead HWBC08



Wilco Part Number	Impedance ohms	Tolerance %	Test Freq	DCR max ohms	Rated A mA max
HWBC08-400-LF	40	±25%	100	0.020	6000
HWBC08-500-LF	50	±25%	100	0.020	6000
HWBC08-600-LF	60	±25%	100	0.020	5000
HWBC08-700-LF	70	±25%	100	0.025	5000
HWBC08-750-LF	75	±25%	100	0.025	5000
HWBC08-800-LF	80	±25%	100	0.025	4000
HWBC08-900-LF	90	±25%	100	0.100	2000
HWBC08-101-LF	100	±25%	100	0.100	2000
HWBC08-151-LF	150	±25%	100	0.100	2000
HWBC08-191-LF	190	±25%	100	0.100	2000
HWBC08-301-LF	300	±25%	100	0.100	2000
HWBC08-471-LF	470	±25%	100	0.100	2000
HWBC08-601-LF	600	±25%	100	0.100	2000
HWBC08-851-LF	850	±25%	100	0.100	2000
HWBC08-102-LF	1000	±25%	100	0.100	2000

Features
 Effective EMI protection
 Low DC resistance
 High soldering heat resistance

Applications
 Computers and Peripheral Equipment
 VCRS, Television
 Cellular Phones
 Digital Communication Equipment
 Various Electronics Equipments
 Circuit Where a Stable Ground is Unavailable

Resistance to Soldering Heat
 Pre-heating: 150 C, 1min
 Solder Temperature: 260±5 C
 Immersion Time: 10±1sec

Physical
 Operating Temperature -55 C-125 C
 Storage Temperature 25±3 C
 Humidity < 80% RH
 2000 per reel